



Monolithic ICs

T-77-11



T-77-21

● Audio Signal Processing (continued)

Type	Function	Package		Features	Reference Catalog
		Configuration	No. of pins		
BA5116	Switchless REC/PB amplifier	DIP	20	Includes all audio amplifiers for the VTR sound signal system. Few external components. Applicable to noise reduction system.	No.3121
BA7751ALS/ BA7751AFS	Switchless REC/PB amplifier	LES/ MFS	24	Includes all audio amplifiers for the VTR sound signal system. Built-in head switch (playback) and head switch driver (record). Type variation corresponds to the difference in control system specs.	No.3121
BA7752LS/ BA7752FS	Switchless REC/PB amplifier	LES/ MFS	24		No.3121
BA7755	Audio high pressure-resistant head switcher	SIP	5	Head switcher with breakdown voltage of $\pm 65V$, usable in pair with BA7751ALS/BA7752LS, BA7757BK has AC breakdown voltage of 120 Vpp (min.) or 160 Vpp (typ.).	No.2962
BA7755A	Audio high pressure-resistant head switcher	SIP	5		No.3121
BA7757BK	Switchless REC/PB amplifier	QFP	32	Headphone amplifier. Built-in line/mic switch. Low supply voltage of 5V and low power consumption – suitable for compact VTRs.	No.3121
BA7765AS	Switchless REC/PB amplifier	DIPS	32	Single-package version now includes high-voltage head switcher (120Vpp Min., $f=70kHz$) compatible with S-VHS equipment, requires very few external components, all necessary functions implemented on a single chip, compatible with noise reduction systems. Type variation corresponds to the difference in control system specs.	No.3121
BA7766AS	Switchless REC/PB amplifier	DIPS	32		
BA7767AS	Switchless REC/PB amplifier	DIPS	32		
BA7700K1	VHS Hi-Fi audio signal processing.	QFP	80	Integrates on a chip the MODEM, PNR, output switch, and electronic variable resistor necessary.	No.3121
BA7703K1	VHS Hi-Fi audio signal processing.	QFP	80	MODEM, PNR, input/output switches and electronic variable resistor required are all integrated on one chip.	No.3121
BA7705K1	VHS-Hi-Fi audio signal processing	QFP	80	Integrates on a chip the MODEM, PNR, output switch, and electronic variable resistor necessary	—
BA7706KS	VHS-Hi-Fi audio signal processing	Shrink QFP	80	Modem, PNR, input switches, output switches, and electronic volume controls required for VHS hi-fi audio circuits all integrated on a single chip. Come in shrink package; ideal for video cameras.	—
New BA7708KS	VHS-Hi-Fi audio signal processing	QFPS	80	Modem, PNR, input switches, output switches, and electronic volume controls required for VHS hi-fi audio circuits all integrated on a single chip. Come in shrink package; ideal for video cameras. Built-in reference input levels – 22dBV	—
BA7056LS	Hi-Fi audio output switcher	LFS	24	Includes all output switches required by a Hi-Fi VTR. Built-in Head Phone amplifier and indicator driver.	No.3121
BA7058LS	Hi-Fi audio output switcher	LFS	24	Includes all output switches required by a Hi-Fi VTR. Built-in Head Phone amplifier and indicator driver. (independent headphone amps.)	No.3121
BA7057S	Hi-Fi audio input switcher	DIPS	22	Includes all required input switchers for Hi-Fi VTR. Built-in muting pulse generating circuit.	—
BA7710S	Hi-Fi audio modem	DIPS	30	Integrates 2ch modulation/demodulation system for VHS-Hi-Fi audio on a single chip. Compact shrink 30-pin package that reduces that number of external parts. Type variation corresponds to the difference in control system specs.	No.3121
BA7711S	Hi-Fi audio modem	DIPS	30		No.3121
BA7720S	Hi-Fi audio peak noise reduction	DIPS	42	Realizes precise encode/decode characteristics through the use of common externally attached components; built-in ALC circuit; two manual and automatic line-input systems. Usable with \pm power supply. Type variation corresponds to the difference in control system specs.	No.3121
BA7721S	Hi-Fi audio peak noise reduction	DIPS	42		No.3121
BA7730S	Hi-Fi audio input and output switcher	DIPS	32	All necessary I/O switchers built-in for Hi-Fi-VTR Usable with \pm power supply. Usable with conventional stereo, SC, BIL and SAP. With EVR. Built-in headphone amplifier. Type variation corresponds to the difference in control system specs.	No.3121
BA7731S	Hi-Fi audio input and output switcher	DIPS	32		No.3121
BA7740S/BA7740FS	Hi-Fi audio signal RE/REC amplifier	DIPS/ MFS	22/24	5V operation; low power consumption; available in small 22-pin shrink DIP or 24-pin shrink MF package.	No.3121
BA7743S/BA7743FS	Hi-Fi audio signal PRE/REC amplifier	DIPS/ MFS	24	Single 5V supply; low power design; internal constant-current REC AGC to eliminate the need for recording current adjustment.	No.3121

● Remote Controller

BA6334	16-operation mode detector	SIP	9	Series resistance value switching method used for two-wire remote control. Capable of selecting 16 modes.	No.3121
BA6340	Infrared remote control reception circuit preamplifier	SIP	8	Amplifies on/off signal of PIN diode and performs peak detection for output. High input sensitivity. A built-in circuit prevents misoperation from large input.	No.3121
BU1301F (base chip)	Encoder for infrared remote controls	MF	20	Capable of operating at low voltage. Includes 32 function keys. Built-in custom code and LED driver for displaying transmission.	—

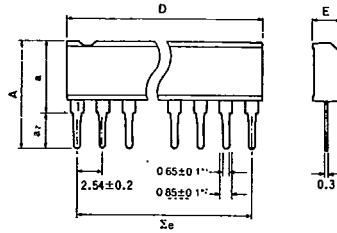
● VTR Motor Drivers

BA6109	Reversible motor driver	SIP-P	10	Built-in motor drive power transistors. Built-in motor stopping brake function. 0.8A drive capability.	No.3121
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Dimensions (Unless otherwise specified, dimensions are shown in Typ. values.)

SIP

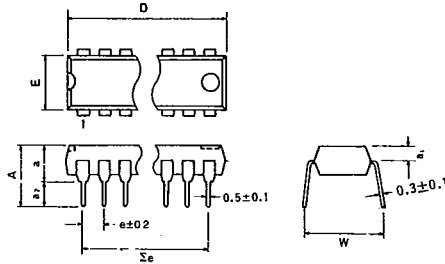


• SIP Dimensions (Unit: mm)

Package	A	a	a ₂	D	Σe	E
SIP 5	9.7	6.2	3.5	12.0	10.16	2.4
SIP 7	9.7	6.2	3.5	17.0	15.24	2.8
SIP 8	10.5	7.0	3.5	19.5	17.78	2.8
SIP 9	10.5	7.0	3.5	22.0	20.32	2.8
SIP 10	10.5	7.0	3.5	25.2	22.86	2.8

*1 SIP 10pin: 0.6 *2 SIP 10pin: 0.8

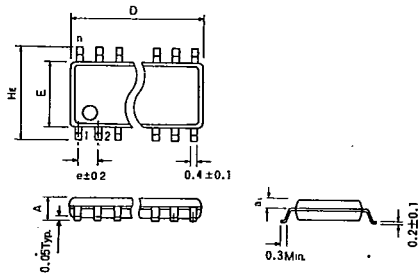
DIP/DIPS



• DIP Dimensions (Unit: mm)

Package	A	a	a ₁	a ₂	D	e	Σe	E	W
DIP 8	6.8	3.6	1.1	3.2	9.3	2.54	7.62	6.5	8.8
DIP 14	6.94	3.65	1.65	3.29	19.4	2.54	15.24	6.5	8.8
DIP 16	6.94	3.65	1.65	3.29	19.4	2.54	17.78	6.5	8.8
DIP 18	6.94	3.65	1.65	3.29	22.9	2.54	20.32	6.5	8.8
DIP 20	7.09	3.65	1.65	3.44	26.3	2.54	22.86	6.5	8.8
DIP 22	7.09	3.65	1.65	3.44	32.0	2.54	25.40	6.5	8.8
DIP 24	7.51	4.22	1.8	3.29	32.0	2.54	27.94	13.8	16.5
DIP 28	7.51	4.22	1.8	3.29	37.1	2.54	33.02	13.8	16.5
DIP 40	7.7	4.5	1.8	3.2	52.3	2.54	48.26	13.8	16.5
DIPS 18	7.35	3.65	1.65	3.7	19.4	1.778	14.224	6.5	8.8
DIPS 22	7.35	3.65	1.65	3.7	19.4	1.778	17.78	6.5	8.8
DIPS 24	7.4	4.0	1.7	3.4	22.8	1.778	19.558	6.5	8.8
DIPS 30	7.9	4.7	1.7	3.2	28.0	1.778	24.892	8.4	11.4
DIPS 32	7.9	4.7	1.7	3.2	28.0	1.778	26.67	8.4	11.4
DIPS 42	7.7	4.5	1.8	3.2	37.1	1.778	35.56	13.8	16.5

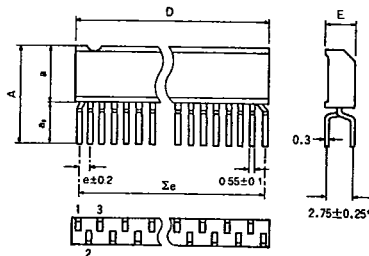
MF/MFS/MFP



• MF Dimensions (Unit: mm)

Package	A	a ₁	D	H _e	e	E
MF 8	1.5	0.65	5.0	6.2	1.27	4.4
MF 14	1.5	0.65	8.7	6.2	1.27	4.4
MF 16	1.5	0.65	10.0	6.2	1.27	4.4
MF 18	1.8	0.8	11.2	7.8	1.27	5.4
MF 20	1.8	0.8	12.5	7.8	1.27	5.4
MF 22	1.8	0.8	13.7	7.8	1.27	5.4
MF 24	1.8	0.8	15.0	7.8	1.27	5.4
MF 28	2.2	1.0	18.5	9.9	1.27	7.5
MFS 16	1.5	0.65	6.6	6.2	0.8	4.4
MFS 20	1.8	0.8	8.7	7.8	0.8	5.4
MFS 24	1.8	0.8	10.0	7.8	0.8	5.4
MFP 24	1.9	0.8	13.7	7.8	0.8	5.4
MFP 28	2.2	0.95	18.5	9.9	0.8	7.5

LF/LFS



• LF Dimensions (Unit: mm)

Package	A	a	a ₂	D	Σe	e	E
LF 9	9.8	5.0	4.8	12.0	10.16	1.27	2.4
LF 12	9.8	5.0	4.8	17.0	13.97	1.27	2.8
LF 16	9.9	5.8	4.1	19.5	19.05	1.27	2.8
LF 18	9.9	5.8	4.1	22.0	21.59	1.27	2.8
LFS 24	10.0	5.8	4.2	22.0	20.447	0.889	2.8

*LFS 24: 2.54±0.25

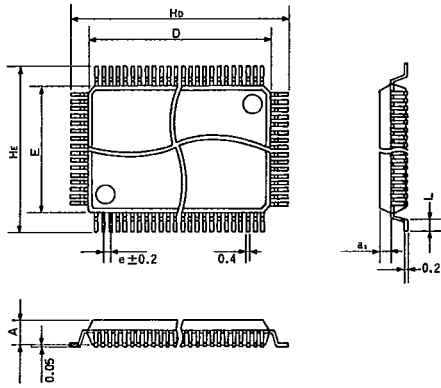


Monolithic ICs



T-90-20

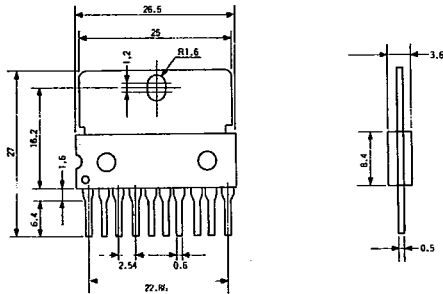
QFP/QFPS



• QFP Dimensions (Unit: mm)

Package	A	a_1	D	e	E	H_E	H_D	L
QFP 32	1.45	0.65	7.0	0.8	7.0	9.0	9.0	0.4
QFP 44	2.15	1.0	10.0	0.8	10.0	14.0	14.0	1.2
QFP 64	2.15	1.0	20.0	1.0	14.0	18.0	24.0	1.2
QFP 80	2.7	1.275	20.0	0.8	14.0	18.0	24.0	1.2
QFPS 56	2.15	1.0	10.0	0.65	10.0	12.4	12.4	0.5
QFPS 80	2.7	1.275	14.0	0.65	14.0	16.4	16.4	0.5
QFPS 100	2.7	1.275	20.0	0.65	14.0	18.0	24.0	1.2

SIP-P 10 pin



SIP-P 12 pin

